



PATENT APPLICATION
Do. No. 9903-014

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Jong-Kon Choi

Serial No. 09/847,620

Examiner: James M. Mitchell

Filed: May 2, 2001

Group Art Unit: 2827

For: METHOD FOR MANUFACTURING DIGITAL MICRO-MIRROR DEVICE
(DMD) PACKAGES

Confirmation No. 5622

BOX NON FEE AMENDMENT
Assistant Commissioner for Patents
Washington, D.C. 20231

RESPONSE TO OFFICE ACTION

Responsive to the Office Action, dated November 19, 2002, please amend the application as follows.

IN THE SPECIFICATION

Please replace the paragraph beginning at page 2, lines 24-25 with the following:

The silicon particles generated during the wafer-breaking step are then removed (step 76).

Please replace the paragraph beginning at page 6, line 22-26, with the following:

As shown in FIGS. 6 through 8, the manufacturing process starts with preparing the wafer 110 (step 191). The silicon wafer 110 comprises a plurality of mirror-driving integrated circuits (not shown) formed by conventional techniques. A plurality of semiconductor chips 112 are formed on the wafer 110. Scribe lines 118 are also formed between the neighboring semiconductor chips 112, where the circuits are not formed.

IN THE CLAIMS

1. (Twice amended) A method for manufacturing a semiconductor package, said method comprising:

providing a wafer including one or more semiconductor chips, each chip comprising